



"Where Two Worlds Meet: SystemC AMS and TLM Interaction"

**Open SystemC Initiative
Interactive Session
DATE 2008**

Welcome !

**Welcome to this open, interactive session organized by the AMS
Working Group:**

"Where Two Worlds Meet: SystemC AMS and TLM Interaction"

Why organizing this event? motivation

- **Objective TLM-2**

- standardize the communications API towards a general-purpose interoperability layer for architecture model-to-model communication

- **Objective AMS extensions**

- Analyze and standardize extensions of SystemC with a semantic for describing non-conservative and conservative systems with continuous-time descriptions for electrical or non-electrical domains

- **Foreseen interaction**

- Use TLM as communication mechanism to interact with AMS subsystems, which use dedicated models of computation and/or solvers

Why we need you? objectives of this session

- **Learning and sharing SystemC AMS and TLM knowledge**
 - interaction between these two SystemC communities
- **Understanding impact and interaction between**
 - OSCI TLM standardization
 - OSCI AMS standardization
- **Creating a common understanding on the relation between SystemC TLM and AMS**
- **Steer future developments / discussions**
- **Networking**

Agenda (1/2)

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|--------------------|--|
| 12:30-12:35 | <i>Welcome</i>
Martin Barnasconi, NXP Semiconductors, The Netherlands |
| 12.35-12.50 | <i>Introduction to SystemC AMS - TLM interaction for SoC Architectures</i>
Martin Barnasconi, NXP Semiconductors, The Netherlands |
| 12.50-13:00 | <i>TLM – AMS Interaction, First Concepts</i>
Karsten Einwich, Fraunhofer, Germany |
| 13.00-13:20 | <i>Connecting SystemC-AMS models and TLM 2.0 models using the loosely-timed coding style with temporal decoupling</i>
Markus Damm, Vienna University of Technology, Austria |

Agenda (1/2)

13.35-14:00 **Interactive Forum/Panel session:**
Where Two Worlds Meet: SystemC AMS and TLM Interaction

Moderator: Martin Barnasconi, NXP Semiconductors

Participants :

Laurent Maillet-Contoz, STM

Victor Reyes, NXP Semiconductors

Karsten Einwich, Fraunhofer

Christoph Grimm, TU Vienna

Francois Pecheux, UPMC/LIP6



Thank you for your participation !